

## **IO-Link Device Transceiver**

### **General Description**

The MAX14821 transceiver is suitable for IO-Link® devices and 24V binary sensors/actuators. All specified IO-Link data rates are supported. In IO-Link applications, the transceiver acts as the physical layer interface to a microcontroller running the data-link layer protocol. Additional 24V digital inputs and outputs are provided. Two internal linear regulators generate common sensor

On-board C/Q and DO drivers are independently configurable for push-pull, high-side (PNP), or low-side (NPN) operation. The device detects the IO-Link C/Q wake-up condition and generates a wake-up signal on the active-low WU output. The C/Q and DI inputs have selectable current loads for use in actuators.

and actuator power requirements: 5V and 3.3V.

An SPI™ interface allows configuration and monitoring of the device. Extensive alarm conditions are detected and communicated through the  $\overline{IRQ}$  output and the SPI interface. The device features reverse-polarity, short-circuit, and thermal protection. All power lines are monitored for undervoltage conditions.

The C/Q and DO drivers are specified for sourcing/sinking up to 100mA.

The device is available in a 2.5mm x 2.5mm, 25-pin WLP and a 4mm x 4mm, 24-pin TQFN package. Both are specified over the extended -40°C to +85°C temperature range.

## **Applications**

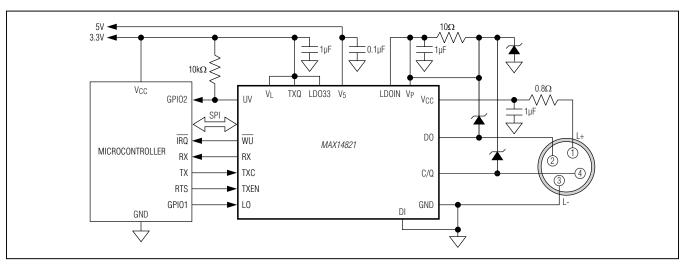
IO-Link Sensors Industrial Sensors and Actuators
IO-Link Actuators

#### **Features**

- IO-Link Specification v.1.0 and v.1.1 Physical Layer-Compliant
- ♦ Supports COM1, COM2, and COM3 Data Rates
- ♦ IO-Link Device Wake-Up Detection
- ♦ Push-Pull, High-Side, or Low-Side Outputs
- ♦ 100mA Specified C/Q Output Drive
- ♦ Auxiliary 24V, 100mA Digital Output
- ♦ Auxiliary 24V Digital Input
- ♦ Optional 6mA/7mA Current Loads at Both 24V Inputs
- ♦ 5V and 3.3V Linear Regulators
- ♦ Reverse-Polarity Protected 24V Supply Output
- ♦ EMI Emission Control Through Slew-Controlled Driver
- ♦ SPI Interface for Configuration and Monitoring
- ♦ 2.5V to 5V Logic Interface Levels
- Reverse-Polarity and Short-Circuit Protection on All 24V Inputs/Outputs
- ♦ High-Temperature Warning and Thermal Shutdown
- ♦ Extensive Fault Monitoring and Reporting
- ♦ -40°C to +85°C Operating Temperature Range
- ♦ 2.5mm x 2.5mm WLP and 4mm x 4mm TQFN Packages

Ordering Information appears at end of data sheet.

### **Typical Operating Circuit**



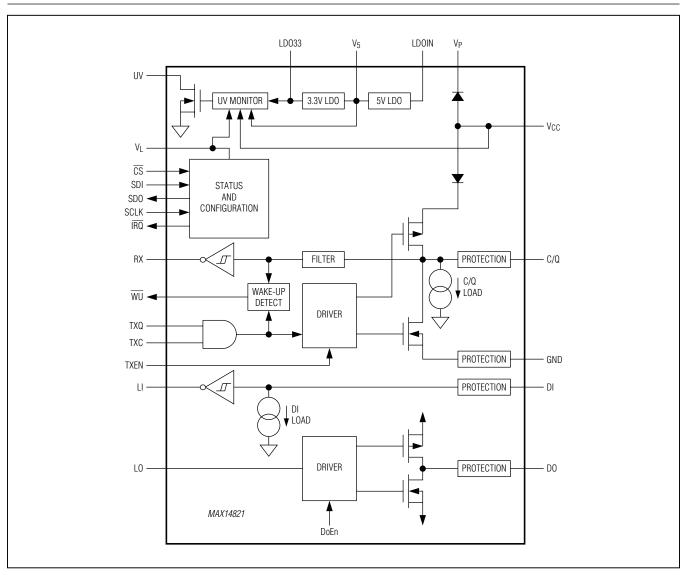
IO-Link is a registered trademark of Profibus User Organization (PNO). SPI is a trademark of Motorola, Inc.

 $\textit{For related parts and recommended products to use with this part, refer to: } \underline{\textbf{www.maximintegrated.com/MAX14821.related}}$ 

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim Integrated's website at www.maximintegrated.com.

# **IO-Link Device Transceiver**

## **Functional Diagram**



## **IO-Link Device Transceiver**

#### **ABSOLUTE MAXIMUM RATINGS**

(All voltages referenced to GND, unless otherwise noted.)	Logic Outputs
V <sub>CC</sub> 40V to +40V	RX, $\overline{WU}$ , LI, SDO, $\overline{IRQ}$ 0.3V to (V <sub>L</sub> + 0.3V)
$V_P$ ( $I_{VP}$ < 50mA) the higher of -0.3V and ( $V_{CC}$ - 1V) to +40V	UV0.3V to +6V
LDOIN0.3V to +40V	Continuous Current Into Any Logic Pin±50mA
$V_5$	Continuous Power Dissipation
LDO330.3V to the lesser of $(V_5 + 0.3V)$ and +6V	TQFN (derate 27.8mW/°C above +70°C)2222mW
V <sub>I</sub> 0.3V to +6V	WLP (derate 22.7mW/°C above +70°C)1816mW
DĪ40V to +40V	Operating Temperature Range40°C to +85°C
C/Q, DOMIN: the higher of -40V and (V <sub>CC</sub> - 40V)	Maximum Junction Temperature+150°C
MAX: the lesser of +40V and $(V_{CC} + 40V)$	Storage Temperature Range65°C to +150°C
Logic Inputs	Lead Temperature (TQFN only; soldering, 10s)+300°C
TXC, TXQ, TXEN, LO, $\overline{\text{CS}}$ , SDI, SCLK0.3V to (V <sub>L</sub> + 0.3V)	Soldering Temperature (reflow)+260°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

### **PACKAGE THERMAL CHARACTERISTICS (Note 1)**

TOTAL	- ,	NAT D
TQFN		WLP
Junction-to-Ambient Thermal Resistance (θ <sub>JA</sub> )36°	C/W	Junction-to-Ambient Thermal Resistance (θ <sub>JA</sub> )44°C/W
Junction-to-Case Thermal Resistance (θ ις)3°	C/W	

**Note 1:** Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a four-layer board. For detailed information on package thermal considerations, refer to <a href="https://www.maximintegrated.com/thermal-tutorial">www.maximintegrated.com/thermal-tutorial</a>.

### DC ELECTRICAL CHARACTERISTICS

 $(V_{CC} = 18V \text{ to } 36V, V_L = 2.3V \text{ to } 5.5V, V_{GND} = 0V;$  all logic inputs at  $V_L$  or GND;  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $V_{CC} = 24V, V_L = 3.3V,$  and  $T_A = +25^{\circ}C,$  unless otherwise noted.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
V <sub>CC</sub> Supply Voltage	V <sub>CC</sub>	For driver operation	9		36	V
V <sub>CC</sub> Supply Current	I <sub>CC</sub>	$V_{CC}$ = 24V, C/Q as input, no load on V <sub>5</sub> or LDO33, LDOIN not connected to V <sub>P</sub> , $V_{LDOIN}$ = 24V		1	2.5	mA
V <sub>CC</sub> Undervoltage-Lockout Threshold	V <sub>CCUVLO</sub>	V <sub>CC</sub> falling	6	7.4	9	V
V <sub>CC</sub> Undervoltage-Lockout Threshold Hysteresis	V <sub>CCUVLO_HYST</sub>			200		mV
V <sub>5</sub> Supply Current	I <sub>5_IN</sub>	LDOIN shorted to $V_5$ , external 5V applied to $V_5$ , no switching, LDO33 disabled		3		mA
V <sub>5</sub> Undervoltage-Lockout Threshold	V <sub>5UVLO</sub>	V <sub>5</sub> falling		2.0		V
V <sub>L</sub> Logic-Level Supply Voltage	VL		2.3		5.5	V
V <sub>L</sub> Logic-Level Supply Current	ΙL	All logic inputs at V <sub>L</sub> or GND			5	μA
V <sub>L</sub> Undervoltage Threshold	V <sub>LUVLO</sub>	V <sub>L</sub> falling	0.65	0.95	1.30	V
5V LDO (V <sub>5</sub> )						
LDOIN Input Voltage Range V <sub>LDO</sub>			7		36	V
LDOIN Supply Current	I <sub>LDOIN</sub>	$V_{LDOIN}$ = 24V, C/Q is configured as an input, no load on $V_5$ or LDO33	·	2.5	5	mA

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# DC ELECTRICAL CHARACTERISTICS (continued)

 $(V_{CC} = 18V \text{ to } 36V, V_L = 2.3V \text{ to } 5.5V, V_{GND} = 0V;$  all logic inputs at  $V_L$  or GND;  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $V_{CC} = 24V, V_L = 3.3V$ , and  $T_A = +25^{\circ}C$ , unless otherwise noted.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS
V <sub>5</sub> Output Voltage Range	V <sub>5</sub>	No load on V <sub>5</sub> , 7V ≤ V <sub>LDOIN</sub> ≤ 36V	4.75	5.00	5.25	V
		$1\text{mA} < I_{\text{LOAD}} < 10\text{mA}, V_{\text{LDOIN}} = 7\text{V},$ 0.1µF bypass capacitor on $V_5$		0.8		
V <sub>5</sub> Load Regulation		$\begin{array}{l} 1\text{mA} < I_{LOAD} < 30\text{mA}, \ V_{LDOIN} = 7\text{V}, \\ 0.1\mu\text{F} \ \text{bypass capacitor on V}_5, \ 10\Omega-1\mu\text{F} \\ \text{compensation network added to V}_5 \end{array}$		0.8		%
3.3V LDO (LDO33)						
LDO33 Output Voltage	V <sub>LDO33</sub>	No load on LDO33	3.1	3.3	3.5	V
LDO33 Undervoltage-Lockout Threshold	V <sub>LDO33UVLO</sub>	V <sub>LDO33</sub> falling		2.4		V
LDO33 Load Regulation		1mA < I <sub>LOAD</sub> < 20mA, V <sub>LDOIN</sub> = 7V		0.25		%
24V INTERFACE						
C/Q Driver Output-Voltage High	V <sub>OH_C/Q</sub>	C/Q high-side enabled, $I_{C/Q} = -100$ mA, $9V \le V_{CC} \le 36V$	V <sub>CC</sub> - 1.3	V <sub>CC</sub> – 1.3		V
C/Q Driver Output-Voltage Low	V <sub>OL_C/Q</sub>	C/Q low-side enabled, $I_{C/Q} = +100$ mA, $9V \le V_{CC} \le 36V$		1.4	3	V
C/Q Driver Source Current Limit	I <sub>OH_C/Q</sub>	C/Q high-side enabled, $V_{C/Q} < (V_{CC} - 3V)$ , $9V \le V_{CC} \le 36V$	+100	+140	+190	mA
C/Q Driver Sink Current Limit	lol_c/q	C/Q low-side enabled, $V_{C/Q} > 3V$ , $9V \le V_{CC} \le 36V$	-190	-140	-100	mA
DO Driver Output-Voltage High	V <sub>OH_DO</sub>	DO high-side enabled, $I_{DO} = +100$ mA, $9V \le V_{CC} \le 36V$	V <sub>CC</sub>	V <sub>CC</sub> -		٧
DO Driver Output-Voltage Low	V <sub>OL_DO</sub>	DO low-side enabled, $I_{DO}$ = -100mA, $9V \le V_{CC} \le 36V$		1.6	3	V
DO Driver Source Current Limit	I <sub>OH_DO</sub>	DO high-side enabled, V <sub>DO</sub> < (V <sub>CC</sub> - 3V)	+100	+135	+190	mA
DO Driver Sink Current Limit	I <sub>OL_DO</sub>	DO high-side enabled, V <sub>DO</sub> > 3V	-190	-135	-100	mA
C/Q, DI Input Voltage Range	V <sub>IN</sub>	For valid RX, LI	-1.0		V <sub>CC</sub> +	V
C/Q Input Threshold High	V <sub>IH_C/Q</sub>	C/Q driver disabled	10.5		13.0	V
C/Q Input Threshold Low	V <sub>IL_C/Q</sub>	C/Q driver disabled	8.0		11.5	V
C/Q Input Hysteresis	V <sub>HYS_C/Q</sub>	C/Q driver disabled	1.0			V
DI Input Threshold High	V <sub>IH_DI</sub>		6.8		8	V
DI Input Threshold Low	V <sub>IL_DI</sub>		5.2		6.4	V
DI Input Hysteresis	V <sub>HYS_DI</sub>		1			V
C/Q Weak Pulldown Current	I <sub>PDC/Q</sub>	C/Q driver disabled, $V_{C/Q} = (V_{CC} - 1V)$	100		400	μΑ

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## **DC ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = 18V \text{ to } 36V, V_L = 2.3V \text{ to } 5.5V, V_{GND} = 0V;$  all logic inputs at  $V_L$  or GND;  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $V_{CC} = 24V, V_L = 3.3V$ , and  $T_A = +25^{\circ}C$ , unless otherwise noted.) (Note 2)

DO Weak Pulldown Current	PARAMETER	SYMBOL	CONDIT	TIONS	MIN	TYP	MAX	UNITS
	DO Weak Pulldown Current	I <sub>PDDO</sub>			40		120	μΑ
DO Input Capacitance	DI Weak Pulldown Current	I <sub>PDDI</sub>		= 36V,	50		300	μΑ
$ \begin{array}{ c c c c }\hline Di \ Input \ Capacitance & C_D   & & & & & & & \\ \hline \hline \textbf{C/Q, Di CURRENT SINK} \\ \hline \textbf{C/Q Load Current} & I_{LLM\_C/Q} & C/Q \ load enabled \ (C/QLoad = 1) & & & & & & \\ \hline \textbf{OV $\le$ V_{C/Q}$ $ $ $ $ $ $ $ $ 6.6 $ $ $ $ $ $ $ $ $ $	C/Q Input Capacitance	C <sub>C/Q</sub>	C/Q driver disabled			40		pF
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	DO Input Capacitance	C <sub>DO</sub>	DO driver disabled			40		pF
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	DI Input Capacitance	C <sub>DI</sub>				20		pF
$ \begin{array}{c c c c c c c c c c c c c c c c c c c $	C/Q, DI CURRENT SINK							
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	C/O Load Current	lu M C/O		$0V \le V_{C/Q} \le 5V$	0		9	mA
$ \begin{array}{ c c c c c c } \hline DI Load Current & ILLM_DI & (DiLoad = 1) & 9V \le V_{DI} & 6 & 7.5 & 9 \\ \hline \hline \textbf{LOGIC INPUTS (TXC, TXQ, TXEN, LO, \overline{CS}, SDI, SCLK)} \\ \hline Logic-Input Voltage Low & V_{IL} & & & & & & & & & & & & & & & & & & &$	O/Q Edua Guironi	'LLIVI_C/Q	(C/QLoad = 1)	-, -,	5	6.6	9	111/
$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	DLL oad Current	lum Di		$0V \le V_{DI} \le 5V$	0		9	mA
Logic-Input Voltage Low       VIL       0.3 x VL         Logic -Input Voltage High       VIH       0.7 x VL         Logic-Input Leakage Current       ILEAK       Logic input = GND or VL       -1       +1         Logic-Input Capacitance       CIN       5         LOGIC OUTPUTS (RX, WU, LI, UV, SDO, IRQ)         Logic-Output Voltage Low       VOL       IOUT = -5mA       0.4         Logic-Output Voltage High       VOHRX, VOHULI, VOHLI, VOHSDO, VOHIRQ, VOHIR	Di Load Guirent	I 'LLM_DI	(DiLoad = 1)	9V ≤ V <sub>DI</sub>	6	7.5	9	
Logic -Input Voltage High  VIH  Logic -Input Voltage High  VIH  Logic -Input Voltage High  VIH  Logic -Input Leakage Current  Logic -Input Leakage Current  Logic -Input Capacitance  CIN  Logic -Input Capacitance  Logic -Input Capacitance  CIN  Logic -Input Capacitance  Logi	LOGIC INPUTS (TXC, TXQ, TX	EN, LO, $\overline{\text{CS}}$ , SDI,	SCLK)					
Logic -Input Voltage High VIH  Logic-Input Leakage Current  Logic-Input Capacitance  CIN  LOGIC OUTPUTS (RX, WU, LI, UV, SDO, IRQ)  Logic-Output Voltage Low  VOL  Logic-Output Voltage High  VOHRX, VOHRV, VOHBO, V	Logic-Input Voltage Low	V <sub>IL</sub>						V
Logic-Input Capacitance       CIN       5         LOGIC OUTPUTS (RX, WU, LI, UV, SDO, IRQ)         Logic-Output Voltage Low       VOL       IOUT = -5mA       0.4         Logic-Output Voltage High       VOHRX, VOHRIV, VOHLIV, VOHSDO, VOHRQ, VOHRQ, VOHRQ, VOHRQ, VOHRQ, VOHRQ       IOUT = 5mA (Note 3)       VL - 0.6         SDO Leakage Current       ILK_SDO       SDO disabled, SDO = GND or VL       -1       +1         THERMAL SHUTDOWN         Thermal Warning Threshold       Die temperature rising, OTemp bit is set       +115         Thermal Warning Threshold       Die temperature falling, OTemp bit is cleared       20         Thermal Shutdown Threshold       Die temperature rising       +150	Logic -Input Voltage High	V <sub>IH</sub>					V	
LOGIC OUTPUTS (RX, WU, LI, UV, SDO, IRQ)         Logic-Output Voltage Low       VOL       IOUT = -5mA       0.4         Logic-Output Voltage High       VOHRX, VOHUI, VOHLI, VOHSDO, VOHIRQ, VOHIRQ	Logic-Input Leakage Current	I <sub>LEAK</sub>	Logic input = GND or	VL	-1		+1	μΑ
Logic-Output Voltage Low  VOL  VOHRX, VOHRX, VOHSDO, VOHIRQ,  SDO Leakage Current  ILK_SDO  SDO disabled, SDO = GND or VL  THERMAL SHUTDOWN  Thermal Warning Threshold  Thermal Warning Threshold Hysteresis  Thermal Shutdown Threshold  Die temperature rising, OTemp bit is set H115  Die temperature falling, OTemp bit is cleared  Thermal Shutdown Threshold  Die temperature rising  10.4  O.4  O.4  O.5  Die temperature rising  Die temperature falling, OTemp bit is cleared  Thermal Shutdown Threshold  Die temperature rising  Die temperature rising  Thermal Shutdown Threshold  Die temperature rising  Die temperature rising  Thermal Shutdown Threshold  Die temperature rising	Logic-Input Capacitance	C <sub>IN</sub>				5		pF
Logic-Output Voltage High  VOHRX, VOHBDO, VOHBO, VO	LOGIC OUTPUTS (RX, $\overline{WU}$ , LI,	UV, SDO, $\overline{IRQ}$ )						
Logic-Output Voltage High  VOHWU, VOHLI, VOHBO, VOHIRQ, VOHBQ, VOHIRQ, SDO Leakage Current  ILK_SDO  SDO disabled, SDO = GND or VL  THERMAL SHUTDOWN  Thermal Warning Threshold Thermal Warning Threshold Hysteresis  Thermal Shutdown Threshold Die temperature rising, OTemp bit is set Leared  Die temperature falling, OTemp bit is cleared  Thermal Shutdown Threshold Die temperature rising  100T = 5mA (Note 3)  VL - 0.6  VL - 1	Logic-Output Voltage Low	V <sub>OL</sub>	I <sub>OUT</sub> = -5mA				0.4	V
THERMAL SHUTDOWN  Thermal Warning Threshold  Die temperature rising, OTemp bit is set +115  Thermal Warning Threshold Hysteresis  Die temperature falling, OTemp bit is cleared  Die temperature rising +150	Logic-Output Voltage High	V <sub>OHWU</sub> , V <sub>OHLI</sub> , V <sub>OHSDO</sub> ,	I <sub>OUT</sub> = 5mA (Note 3)				V	
Thermal Warning Threshold  Die temperature rising, OTemp bit is set +115  Thermal Warning Threshold Hysteresis  Thermal Shutdown Threshold  Die temperature falling, OTemp bit is cleared  Die temperature rising +150	SDO Leakage Current	I <sub>LK_SDO</sub>	SDO disabled, SDO = GND or V <sub>L</sub>		-1		+1	μΑ
Thermal Warning Threshold Hysteresis  Die temperature falling, OTemp bit is cleared  Thermal Shutdown Threshold  Die temperature rising  +150	THERMAL SHUTDOWN							
Hysteresis cleared 20 Thermal Shutdown Threshold Die temperature rising +150	Thermal Warning Threshold		Die temperature rising, OTemp bit is set			+115		°C
	_		' '		20		°C	
The small Chutdayur I hydroxesia	Thermal Shutdown Threshold		Die temperature rising			+150		°C
mermai Shuldown Hysteresis 20	Thermal Shutdown Hysteresis					20		°C

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### **AC ELECTRICAL CHARACTERISTICS**

 $(V_{CC}=18V\ to\ 36V,\ V_L=2.3V\ to\ 5.5V,\ V_{GND}=0V;\ all\ logic\ inputs\ at\ V_L\ or\ GND;\ T_A=-40^{\circ}C\ to\ +85^{\circ}C,\ unless\ otherwise\ noted.\ Typical\ values\ are\ at\ V_{CC}=24V,\ V_L=3.3V,\ and\ T_A=+25^{\circ}C,\ unless\ otherwise\ noted.)$ 

PARAMETER	SYMBOL	CONDITIONS		MIN	TYP	MAX	UNITS
C/Q, DO, DI INTERFACES							ļ.
Data Rate	DR	HiSlew = 1	4.8		230.4	khno	
Dala nate		HiSlew = 0		4.8	38.4		kbps
DRIVER (C/Q, DO)							
Driver Low-to-High Propagation	t·	Push-pull or high-side (PNP)	HiSlew = 1		0.5	2	110
Delay	<sup>t</sup> PDLH	configuration, Figure 1	HiSlew = 0		1.6	5	μs
Driver High-to-Low Propagation	t·	Push-pull or low-side (NPN)	HiSlew = 1		0.5	2	110
Delay	<sup>t</sup> PDHL	configuration, Figure 1	HiSlew = 0		1.6	5	μs
Driver Skew	tSKEW	ItpDLH - tpDHLI			0.1	2	μs
Driver Dies Tiese		Push-pull or high-side (PNP)	HiSlew = 1		0.4	1.7	
Driver Rise Time	t <sub>RISE</sub>	configuration, Figure 1	HiSlew = 0		1.5	4	μs
Deixon Fall Time		Push-pull or low-side (NPN)	HiSlew = 1		0.4	1.7	
Driver Fall Time	tFALL	configuration, Figure 1	HiSlew = 0		1.4	4	- µs
Driver Enable Time High		Push-pull or high-side (PNP) Hi	HiSlew = 1		0.3	1	
	t <sub>ENH</sub>	configuration, Figure 3	HiSlew = 0		0.8	7	μs
Driver Enable Time Low	t <sub>ENL</sub>	Push-pull or low-side (NPN) configuration, Figure 2	HiSlew = 1		0.3	1	
			HiSlew = 0		0.9	7	μs
D' - D' - I - T' I - I		Push-pull or high-side (PNP)	HiSlew = 1		1.6	3	
Driver Disable Time High	t <sub>DISH</sub>	configuration, Figure 2 (Note 4)	HiSlew = 0		1.6	3	- µs
D: D: II T: I		Push-pull or low-side (NPN)	HiSlew = 1		0.1	3	
Driver Disable Time Low	t <sub>DISL</sub>	configuration, Figure 3 (Note 4)	HiSlew = 0		0.1	3	- µs
RECEIVER (C/Q, DI) (Figure 4)						-	
Receiver Low-to-High		RxFilter = 1			0.2	2	
Propagation Delay	<sup>t</sup> PRLH	RxFilter = 0			0.4	2	μs
Receiver High-to-Low		RxFilter = 1			0.3	2	
Propagation Delay	<sup>t</sup> PRHL	RxFilter = 0			0.5	2	μs
WAKE-UP DETECTION (Figure 5	5)					-	1
Wake-Up Input Minimum Pulse Width	twumin			30	40	50	μs
Wake-Up Input Maximum Pulse Width	t <sub>WUMAX</sub>			120	140	160	μs
WU Output Low Time	t <sub>WUL</sub>	Valid wake-up condition on C/	Q	120	190	260	μs

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### **AC ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{CC} = 18V \text{ to } 36V, V_L = 2.3V \text{ to } 5.5V, V_{GND} = 0V;$  all logic inputs at  $V_L$  or GND;  $T_A = -40^{\circ}C$  to  $+85^{\circ}C$ , unless otherwise noted. Typical values are at  $V_{CC} = 24V, V_L = 3.3V,$  and  $T_A = +25^{\circ}C,$  unless otherwise noted.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS			
SPI TIMING (CS, SCLK, SDI, SDO) (Figure 6)									
SCLK Clock Period	t <sub>CH+CL</sub>		83.3			ns			
SCLK Pulse-Width High	t <sub>CH</sub>		41.65			ns			
SCLK Pulse-Width Low	t <sub>CL</sub>		41.65			ns			
CS Fall to SCLK Rise Time	t <sub>CSS</sub>		20			ns			
SCLK Rise to CS Rise Hold Time	tcsh		20			ns			
SDI Hold Time	t <sub>DH</sub>		10			ns			
SDI Setup Time	t <sub>DS</sub>		10			ns			
Output Data Propagation Delay	t <sub>DO</sub>				32	ns			
SDO Rise and Fall Times	t <sub>FT</sub>				20	ns			
Minimum CS Pulse	tcsw		76.8			ns			

Note 2: All devices are 100% production tested at  $T_A = +25$ °C. Limits over the operating temperature range are guaranteed by design.

Note 3: UV is an open-drain output. Connect UV to a voltage less than 5.5V through an external pullup resistor.

Note 4: Disable time measurements are load dependent.

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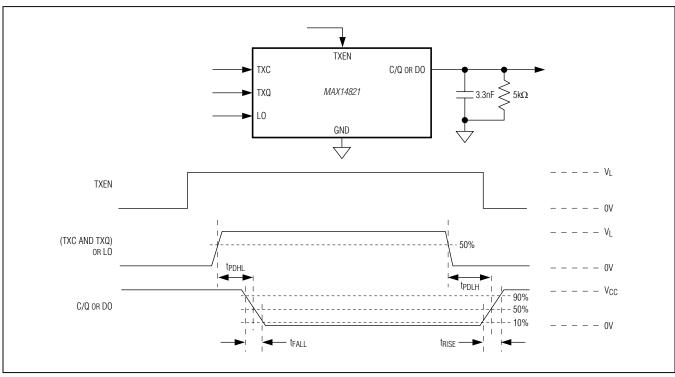


Figure 1. C/Q and LO Driver Propagation Delays and Rise/Fall Times

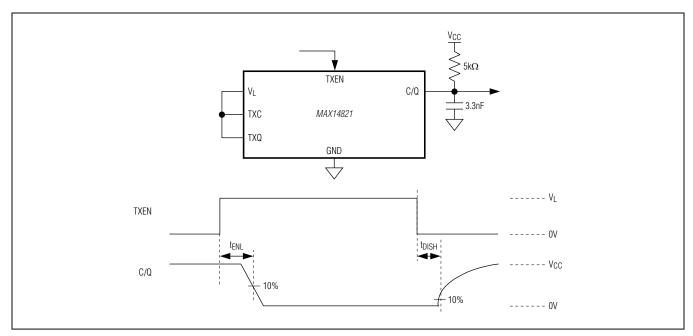


Figure 2. C/Q Driver Enable Low and Disable High Timing with External Pullup Resistor

# **IO-Link Device Transceiver**

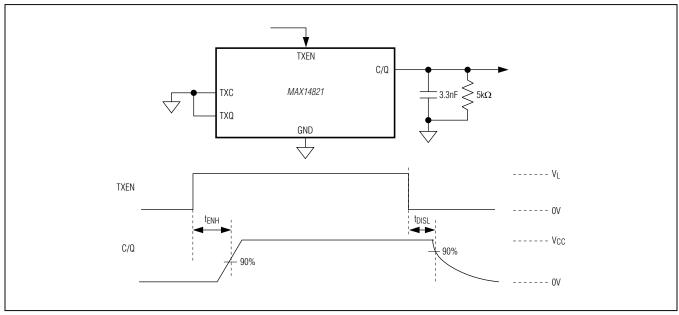


Figure 3. C/Q Driver Enable High and Disable Low Timing

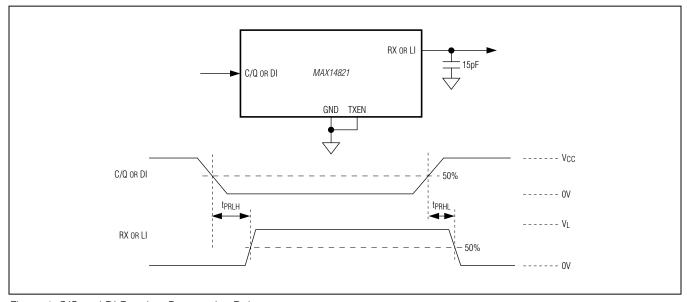


Figure 4. C/Q and DI Receiver Propagation Delays

# **IO-Link Device Transceiver**

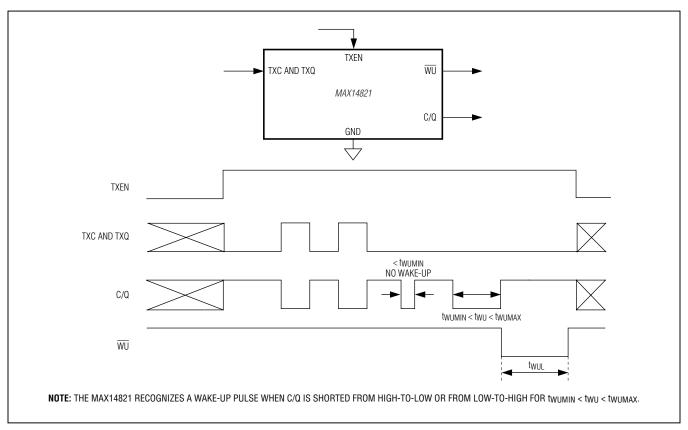


Figure 5. Wake-Up Detection Timing

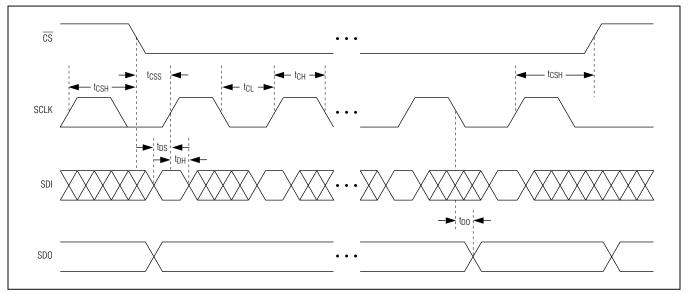
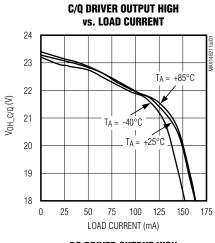


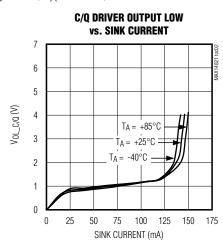
Figure 6. SPI Timing Diagram

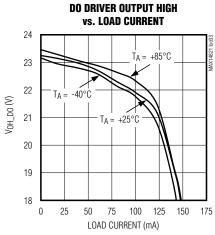
## **IO-Link Device Transceiver**

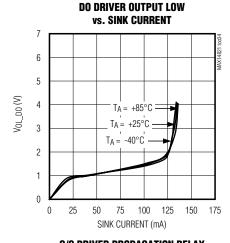
## **Typical Operating Characteristics**

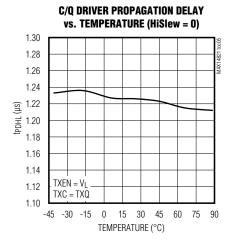
(V<sub>CC</sub> = 24V, LDOIN = V<sub>P</sub>, V<sub>L</sub> = LDO33, C/Q and DO in push-pull configuration, T<sub>A</sub> = +25°C, unless otherwise noted.)

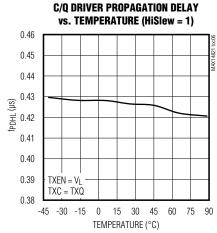








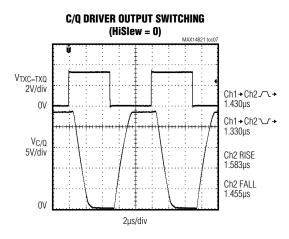


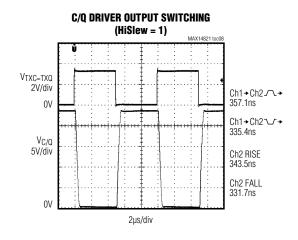


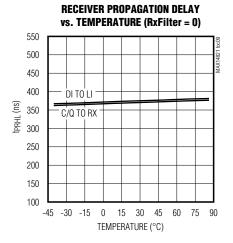
# **IO-Link Device Transceiver**

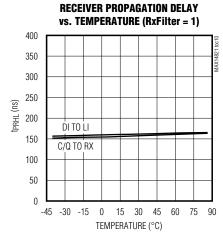
### **Typical Operating Characteristics (continued)**

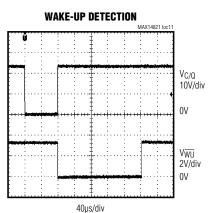
 $(V_{CC} = 24V, LDOIN = V_P, V_L = LDO33, C/Q$ and DO in push-pull configuration,  $T_A = +25$ °C, unless otherwise noted.)

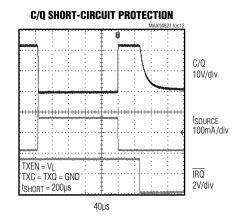








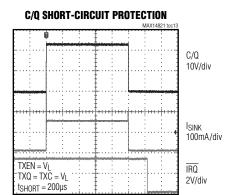




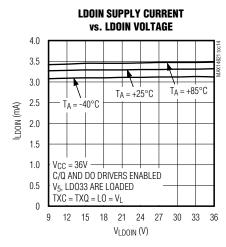
## **IO-Link Device Transceiver**

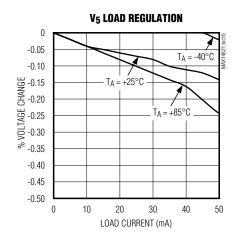
### **Typical Operating Characteristics (continued)**

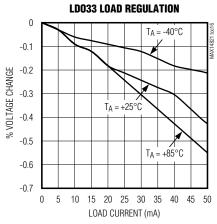
 $(V_{CC} = 24V, LDOIN = V_P, V_L = LDO33, C/Q$ and DO in push-pull configuration,  $T_A = +25$ °C, unless otherwise noted.)

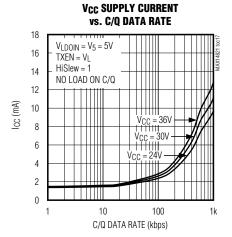


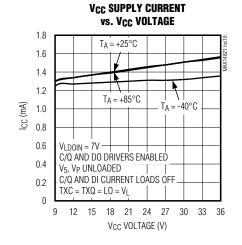
40µs





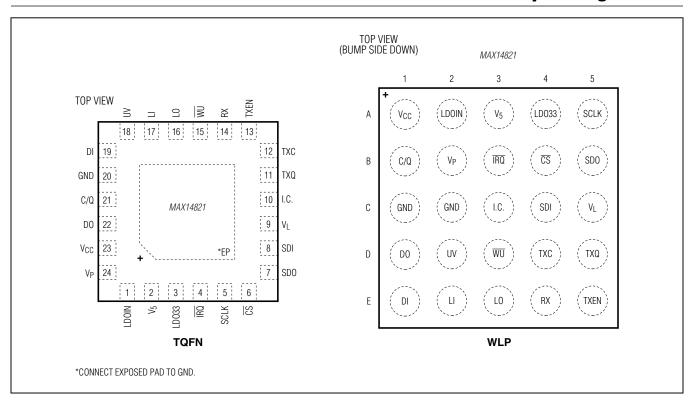






# **IO-Link Device Transceiver**

## **Pin/Bump Configurations**



# **Pin/Bump Descriptions**

PIN	1		FUNCTION
TQFN-EP	WLP	NAME	FUNCTION
1	A2	LDOIN	5V Linear Regulator Input. Bypass LDOIN to GND with a 0.1μF ceramic capacitor.
2	А3	V <sub>5</sub>	5V Power-Supply Input and 5V Linear Regulator Output. Bypass $V_5$ to GND with a $0.1\mu F$ ceramic capacitor for 10mA load capability. Add the recommended compensation network to increase the source capability to 30mA. See the <i>5V and 3.3V Linear Regulators</i> section for more information.
3	A4	LDO33	3.3V Linear Regulator Output. Bypass LDO33 to GND with a 1µF ceramic capacitor.
4	В3	ĪRQ	Active-Low Interrupt Request Output. $\overline{\text{IRQ}}$ is a push-pull output referenced to $V_L$ .
5	A5	SCLK	SPI Clock Input
6	B4	CS	Active-Low SPI Chip-Select Input
7	B5	SDO	SPI Serial-Data Output
8	C4	SDI	SPI Serial-Data Input
9	C5	VL	Logic-Level Supply Input. $V_L$ defines the logic levels on all the logic inputs and outputs. Bypass $V_L$ to GND with a 0.1 $\mu$ F ceramic capacitor.
10	С3	I.C.	Internally Connected. Connect to V <sub>L</sub> or leave unconnected.

# **IO-Link Device Transceiver**

# Pin/Bump Descriptions (continued)

PII	N		
TQFN-EP	WLP	NAME	FUNCTION
11	D5	TXQ	Transmit Level Input. The logic on the C/Q output is the inverse logic level of the signals on the TXC and TXQ inputs. TXQ is ANDed with TXC. Drive TXQ high if not in use.
12	D4	TXC	Transmit Communication Input. The logic on the C/Q output is the inverse logic level of the signals on the TXC and TXQ inputs. TXC is ANDed with TXQ. Drive TXC high if not in use.
13	E5	TXEN	Transmitter Enable. Drive TXEN high to enable the C/Q transmitter. TXEN is referenced to V <sub>L</sub> .
14	E4	RX	Receiver Output. RX is the inverse logic level of C/Q. RX is always high when the RxDis bit in the CQConfig register is set to 1.
15	D3	WU	Active-Low Wake-Up Output. WU is a push-pull output referenced to V <sub>L</sub> . WU pulses low for 190µs (typ) when a valid wake-up pulse is detected on the C/Q line.
16	E3	LO	Logic Input of the DO Output. LO is the logic input that drives DO. LO is referenced to V <sub>L</sub> .
17	E2	LI	Logic Output of the 24V DI Logic Input. LI is the inverse logic of DI. LI is referenced to V <sub>L</sub> .
18	D2	UV	Open-Drain Undervoltage Indicator Output. In case of an undervoltage, the UV open-drain transistor is off.
19	E1	DI	24V Logic-Level Digital Input
20	C1, C2	GND	Ground
21	B1	C/Q	SIO/IO-Link Data Input/Output. Drive TXEN high to enable the C/Q driver. The logic on the C/Q output is the inverse logic level of the signals on the TXC and TXQ inputs. RX is the logic inverse of C/Q. The C/Q driver output level can be set by the TXC/TXQ inputs or programmed by the Q bit. The level on C/Q can be read by the RX ouput or the QLvI bit.
22	D1	DO	24V Logic-Level Digital Output. DO is the inverse logic level of the LO input and can be digitally controlled through the DIOConfig register.
23	A1	V <sub>CC</sub>	Power-Supply Input. Bypass V <sub>CC</sub> to GND with a 1µF ceramic capacitor.
24	B2	V <sub>P</sub>	Protected 24V Supply Output. V <sub>P</sub> is one diode drop below V <sub>CC</sub> . V <sub>P</sub> is reverse-polarity protected and can be used as a 24V protected supply to the sensor or actuator electronics.
_	_	EP	Exposed Pad (TQFN Only). Connect EP to GND.

## **IO-Link Device Transceiver**

### **Detailed Description**

The MAX14821 is a sensor/actuator transceiver designed for IO-Link device applications supporting all the specified IO-Link data rates. In IO-Link applications, the device acts as the physical layer interface to a microcontroller running the data-link layer protocol. The device contains an additional 24V digital input and an additional 24V digital output. Two internal linear regulators generate common sensor and actuator power requirements: 5V and 3.3V.

The device detects IO-Link wake-up conditions on the C/Q line and generates a wake-up signal on the  $\overline{WU}$  output. The C/Q and DO drivers are independently configurable to any one of three driver output types: push-pull, high-side (PNP), or low-side (NPN).

The C/Q and DI inputs have selectable current sinks that can be enabled for use in actuators where the master requires a Type 2 load. The device is configured and monitored through an SPI interface. Extensive alarms are available through SPI.

#### 24V Interface

The device features an IO-transceiver interface capable of operating with voltages up to 36V. This is the 24V interface and includes the C/Q input/output, the logic-level digital output (DO), and the logic-level digital input (DI).

#### Configurable Drivers

The device features selectable push-pull, high-side (PNP), or low-side (NPN) switching drivers at C/Q and DO.

Set the C/Q\_N/P and C/Q\_PP bits in the CQConfig register to select the driver mode for the C/Q driver. When configured as a push-pull output, C/Q switches between V<sub>P</sub> and ground. Set the C/Q\_PP bit to 1 to select push-pull operation at C/Q. Set the C/Q\_PP bit to 0 to configure the C/Q output for open-drain operation. The C/Q\_N/P bit selects NPN or PNP operation when C/Q is configured as an open-drain output.

Set the DoN/P and DoPP bits in the DIOConfig register to select the driver mode for the DO output. When configured as a push-pull output, DO switches between  $V_{CC}$  and ground. Set the DoPP bit to 1 for push-pull operation. The DoN/P bit selects NPN or PNP operation when DO is configured as an open-drain output. Set the DoPP bit to 0 to select high-side or low-side operation at DO.

#### C/Q Driver and Receiver

The TXEN input enables the C/Q driver. Drive TXEN high to enable the C/Q driver. Drive TXEN low to disable the driver.

The C/Q driver is specified to supply up to 100mA DC load current.

The HiSlew bit increases the slew rate of the C/Q and DO driver outputs. Set HiSlew to 1 for data rates of 230kbps or higher. Set HiSlew to 0 to reduce both the C/Q and DO driver slew rates to reduce EMI emission and reflections.

The C/Q receiver is always on. Disable the RX output through the RxDis bit in the CQConfig register. Set the RxDis bit to 1 to set the RX output high. Set the RxDis bit to 0 for normal receive operation.

The C/Q receiver has an analog lowpass filter to reduce high-frequency noise present on the line. Set the RxFilter bit in the CQConfig register to 0 to set the filter corner frequency to 500kHz (typ). Set the RxFilter bit to 1 to set the corner frequency of the filter to 1MHz (typ). Noise filters are present on both the C/Q and DI receivers and are controlled simultaneously by the RxFilter bit.

#### C/Q Fault Detection

The device registers a C/Q fault condition under either of two conditions:

- 1) When it detects a short circuit for longer than 140µs (typ). A short condition exists when the C/Q driver's load current exceeds the 140mA (typ) current limit.
- 2) When it detects a voltage level error at the C/Q output. A voltage level error occurs when the C/Q driver is configured for open-drain operation (NPN or PNP), the driver is turned off, and the C/Q voltage is not pulled to exceed the C/Q receiver's threshold levels (< 8V or > 13V) by the external supply.

When a C/QFault error occurs, the C/QFault and C/QFaultInt bits are set,  $\overline{IRQ}$  asserts, and the driver is turned off 240µs (typ) after the start of the fault condition.

When a short-circuit event occurs on C/Q, the driver enters autoretry mode. In autoretry mode the device periodically checks whether the short is still present and attempts to correct the driver output. Autoretry attempts last for 240µs (typ) and occur every 26ms (typ).

## **IO-Link Device Transceiver**

#### **DO Fault Detection**

The device registers a DoFault event when a short circuit is present at the DO output for 440µs. A short condition exists when the load current on the DO driver exceeds the 135mA (typ) DO current limit. When a short-circuit condition is detected, the DO driver enters autoretry mode. In autoretry mode the device periodically checks whether the error is still present. Autoretry attempts last for 440µs (typ) and occur every 26ms (typ). When a DoFault error is detected, the DoFault and DoFaultInt bits are set,  $\overline{IRQ}$  asserts, and the driver is turned off 440µs (typ) after the start of the DO faults.

#### Reverse-Polarity Protection

The device is protected against reverse-polarity connections on  $V_{CC}$ , C/Q, DO, DI, and GND. Any combination of these pins can be connected to DC voltages up to 40V (max). A short to 40V results in a current flow of less than  $500\mu A$ .

Ensure that the maximum voltage between any of these pins does not exceed 40V.

#### **5V and 3.3V Linear Regulators**

The device includes two internal regulators to generate 5V (V<sub>5</sub>) and 3.3V (LDO33). LDO5 is specified for 10mA total external load current (i.e., LDO33 + V5) when bypassed with a 0.1µF capacitor to ground. Add the compensation network shown in Figure 7 to draw up to 30mA of total external load current from the 5V LDO. LDO33 is specified at 20mA. The input of V<sub>5</sub>, LDOIN, can be powered from V<sub>P</sub>, the protected 24V supply output, or to another voltage in the 7V to 36V range.

If the external circuits that are powered by the linear regulators require an input bypass capacitance larger than 100nF for 5V or 1µF for 3.3V, a compensation network must be added on V5 and/or LDO33. The compensation network consists of a 10 $\Omega$  series resistor and a capacitor equal to the value required by the external circuit, as shown in Figure 14. The capacitors C33\* and C5\* in Figure 14 represent the capacitance required by the external circuits. Figure 14 does not show any protection diodes for simplicity.

When the internal 5V LDO is not used, V5 becomes the supply input for the internal analog and digital functions and thus has to be supplied externally so that the MAX14820 operates normally. The 5V LDO can be disabled by connecting LDOIN to  $V_5$ . Apply an external voltage of 4.75V to 5.25V to  $V_5$  when the LDO is disabled.

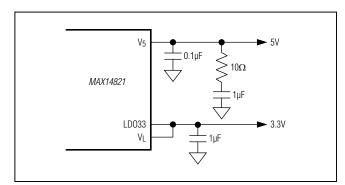


Figure 7. V<sub>5</sub> Compensation Network

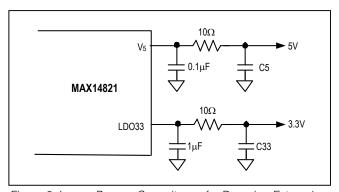


Figure 8. Larger Bypass Capacitance for Powering External Circuits

Use the LDO33Dis bit in the Mode register to disable LDO33. See the <u>Mode Register [R1, R0] = [1,1]</u> section for more information.  $V_5$  and LDO33 are not protected against short circuits.

#### **Power-Up**

The C/Q and DO driver outputs and the UV output are high impedance when  $V_{CC}$ ,  $V_5$ ,  $V_L$ , and/or LDO33 voltages are below their respective undervoltage thresholds during power-up. UV goes low and the drivers are enabled when all these voltages exceed their respective undervoltage-lockout thresholds.

The drivers are automatically disabled if  $V_{CC}$ ,  $V_5$ , or  $V_L$  falls below its threshold.

#### **Undervoltage Detection**

The device monitors V<sub>CC</sub>, V<sub>5</sub>, V<sub>L</sub>, and optionally LDO33 for undervoltage conditions. UV is high impedance when any monitored voltage falls below its UVLO threshold.

 $V_{CC}$ ,  $V_5$ , and  $V_L$  undervoltage detection cannot be disabled. When  $V_{CC}$  falls below the  $V_{CCUVLO}$  threshold, the UV24 and UV24Int bits are set, UV asserts high, and  $\overline{IRQ}$  asserts low.

## **IO-Link Device Transceiver**

The SPI register contents are unchanged while  $V_5$  is present, regardless of the state of  $\underline{V_{CC}}$  and LDO33. The SPI interface is not accessible and  $\overline{IRQ}$  is not available when UV is asserted due to a  $V_5$  or  $V_L$  undervoltage event.

When the internal 3.3V LDO regulator voltage ( $V_{LDO33}$ ) falls below the LDO33 undervoltage-lockout threshold, the UV33Int bit in the Status register is set and  $\overline{IRQ}$  asserts. UV asserts if the UV33En bit in the Mode register is set to 1.

The UV output deasserts once the undervoltage condition is removed; however, bits in the Status register and the  $\overline{\mbox{IRQ}}$  output are not cleared until the Status register has been read.

#### **Wake-Up Detection**

The device detects an IO-Link wake-up condition on the C/Q line in push-pull, high-side (PNP), or low-side (NPN) operation modes. A wake-up condition is detected when the C/Q output is shorted for 80µs (typ). WU pulses low for 190µs (typ) when the device detects a wake-up pulse on C/Q (Figure 5).

Set the WulntEn bit in the Mode register to set the Wulnt bit in the Status register and generate an interrupt on  $\overline{IRQ}$  when a wake-up pulse is detected. Wulnt is set and  $\overline{IRQ}$  asserts immediately after C/Q is released when WulntEn = 1.

#### Thermal Protection and Considerations

The internal LDOs and drivers can generate more power than the package for the device can safely dissipate. Ensure that the driver LDO loading is less than the package can dissipate. Total power dissipation for the device is calculated using the following equation:

$$P_{TOTAL} = P_{C/Q} + P_{DO} + P_5 + P_{LDO33} + P_Q + P_{CLCQ} + P_{CLDI}$$

where  $P_{C/Q}$  is the power generated in the C/Q driver,  $P_{DO}$  is the power dissipated by the DO driver,  $P_5$  and  $P_{LDO33}$  are the power generated by the LDOs,  $P_Q$  is the quiescent power generated by the device, and  $P_{CLCQ}$  and  $P_{CLDI}$  are the power generated in the C/Q and DI current sinks.

Ensure that the total power dissipation is less than the limits listed in the *Absolute Maximum Ratings* section.

Use the following to calculate the power dissipation (in mW) due to the C/Q driver:

$$P_{C/Q} = [I_{C/Q}(max)] \times [0.5 + 7 \times I_{C/Q}(max)]$$

Calculate the internal power dissipation of the DO driver using the following equation:

$$P_{DO} = [I_{DO}(max)] \times [0.5 + 7 \times I_{DO}(max)]$$

Calculate the power dissipation in the 5V LDO, V<sub>5</sub>, using the following equation:

$$P_5 = (V_{LDOIN} - V_5) \times I_5$$

where  $\mbox{\scriptsize I}_{5}$  includes the  $\mbox{\scriptsize I}_{LDO33}$  current sourced from LDO33.

Calculate the power dissipated in the 3.3V LDO, LDO33, using the following equation:

$$P_{LDO33} = 1.7V \times I_{LDO33}$$

Calculate the quiescent power dissipation in the device using the following equation:

$$P_{O} = I_{CC}(max) \times V_{CC}(max)$$

If the current sinks are enabled, calculate their associated power dissipation as:

$$P_{CLCQ} = I_{LLM\_C/Q}(max) \times V_{C/Q}(max)$$
  
 $P_{CLDI} = I_{LLM\_DI}(max) \times V_{DI}(max)$ 

#### Overtemperature Warning

Bits in the Status and Mode registers are set when the temperature of the device exceeds +115°C (typ). The OTempInt bit in the Status register is set and  $\overline{IRQ}$  asserts when the OTemp bit in the Mode register is set. Read the Status register to clear the OTempInt bit and  $\overline{IRQ}$ .

The OTemp bit is cleared when the die temperature falls to +95°C.

The device continues to operate normally unless the die temperature reaches the +150°C thermal shutdown threshold, when the device enters thermal shutdown.

#### Thermal Shutdown

When the die temperature rises above the +150°C (typ) thermal shutdown threshold, the C/Q and DO drivers and the C/Q and DI current loads are automatically turned off. The internal 3.3V and 5V LDOs remain on during thermal shutdown, if enabled. If the internal or external V5 supply remains on during thermal shutdown (which is always true in case of the internal V5 regulator), the register contents are maintained and SPI communication is available.

When the die temperature falls below the thermal shutdown threshold plus hysteresis, the C/Q and DO drivers and C/Q and DI current sinks turn on automatically.

## **IO-Link Device Transceiver**

### **Register Functionality**

The device has four 8-bit-wide registers for configuration and monitoring (Table 1).

### **Table 1. Register Summary**

REGISTER	R1	R0	D7	D6	D5	D4	D3	D2	D1	D0
Status	0	0	WuInt	DoFaultInt	DiLvl	QLvI	C/QFaultInt	UV33Int	UV24Int	OTempInt
CQConfig	0	1	RxFilter	HiSlew	C/Q_N/P	C/Q_PP	C/QDEn	Q	RxDis	C/QLoad
DIOConfig	1	0	Dolnv	DoAv	DoN/P	DoPP	DoEn	DoBit	LiDis	DiLoad
Mode	1	1	RST	WuIntEn	DoFault	C/QFault	UV24	OTemp	UV33En	LDO33Dis

R1/R0 = Register address.

#### **Status Register [R1, R0] = [0,0]**

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Bit Name	WuInt	DoFaultInt	DiLvI	QLvl	C/QFaultInt	UV33Int	UV24Int	OTempInt
Read/Write	R	R	R	R	R	R	R	R
POR State	0	0	X	X	0	0	0	0
Reset Upon Read	Yes	Yes	No	No	Yes	Yes	Yes	Yes

X = Unknown. These bits are dependent on the DI logic and C/Q inputs.

The Status register reflects the logic levels of C/Q and DI and shows the source of interrupts that cause an  $\overline{IRQ}$  hardware interrupt. The  $\overline{IRQ}$  interrupt is asserted when an alarm condition (OTemp, UV33Int, UV24, C/QFault, DoFault, WuInt) is detected. All bits in the Status register are read-only. The interrupt bits return to the default state after the Status register is read. If a C/Q or DO fault condition persists, the associated interrupt bits are immediately set after the Status register is read.

BIT	NAME	DESCRIPTION
D7	Wulnt	<b>Wake-Up Interrupt Request.</b> Wulnt is set when an IO-Link wake-up request pulse is detected on C/Q and the WulntEn bit in the Mode register is set. $\overline{IRQ}$ asserts when Wulnt is set to 1. Read the Status register to clear the Wulnt bit and deassert $\overline{IRQ}$ .
D6	DoFaultInt	<b>DO Fault Interrupt.</b> DoFaultInt interrupt bit and DoFault bit (in the Mode register) are set when a fault condition occurs on the DO driver output. The device registers a fault condition when a short circuit or voltage fault is detected on DO (see the <i>DO Fault Detection</i> section for more information).  ÎRQ asserts when DoFaultInt is 1. Read the Status register to clear the DoFaultInt bit and deassert IRQ.
D5	DiLvl	<b>DI Logic Level.</b> The DiLvI bit mirrors the current logic level at the DI input. It is the inverse of the LI output and is always active regardless of the state of the LiDis bit (Table 2). DiLvI does not affect $\overline{\mbox{IRQ}}$ . DiLvI is not changed when the Status register is read.

# **IO-Link Device Transceiver**

BIT	NAME	DESCRIPTION
D4	QLvl	<b>C/Q Logic Level.</b> The $\overline{\mathbb{Q}}$ Lvl bit is the inverse of the logic level at C/Q. $\overline{\mathbb{Q}}$ Lvl is 1 when the C/Q input level is low (< 8V) and is 0 when the C/Q logic level is high (> 13V) (Table 3). $\overline{\mathbb{Q}}$ Lvl remains active when the C/Q receiver is disabled (RxDis = 1). $\overline{\mathbb{Q}}$ Lvl does not affect $\overline{\mathbb{R}}$ Q. $\overline{\mathbb{Q}}$ Lvl is not changed when the Status register is read.
D3	C/QFaultInt	<b>C/Q Fault Interrupt.</b> The C/QFaultInt interrupt bit and C/QFault bit (in the Mode register) are set when a short circuit or voltage fault occurs on the C/Q driver output (see the $C/Q$ Fault Detection section for more information). $\overline{IRQ}$ asserts when C/QFault is 1. Read the Status register to clear the C/QFaultInt bit and deassert $\overline{IRQ}$ .
D2	UV33Int	Internal 3.3V LDO (LDO33) Undervoltage Warning. Both the UV33Int interrupt bit and the UV33En bit (in the Mode register) are set when $V_{LDO33}$ falls below the 2.4V LDO33 undervoltage threshold. If UV33En is set in the Mode register, $\overline{IRQ}$ asserts low when the UV33Int bit is 1. Read the Status register to clear the UV33Int bit and deassert $\overline{IRQ}$ . Set the UV33En bit to 1 in the Mode register to enable undervoltage monitoring for UV33Int. When enabled, UV asserts high when the UV33Int bit is 1. UV deasserts when $V_{LDO33}$ rises above the LDO33 undervoltage threshold.
D1	UV24Int	<b>V<sub>CC</sub> Undervoltage Interrupt.</b> The UV24Int interrupt bit and the UV24 bit (in the Mode register) are set when the V <sub>CC</sub> voltage falls below the 7.4V undervoltage threshold. $\overline{\text{IRQ}}$ asserts low when the UV24Int bit is 1. Read the Status register to clear the UV24Int bit and deassert $\overline{\text{IRQ}}$ . V <sub>CC</sub> undervoltage detection cannot be disabled.
D0	OTempInt	Overtemperature Warning. The OTempInt interrupt bit and the OTemp bit (in the Mode register) are set when a high-temperature condition is detected by the device. OTemp is set when the temperature of the die exceeds +115°C (typ). OTempInt is set and IRQ asserts when the OTemp bit is 1. The OTempInt bit is cleared and IRQ deasserts when the Status register is read.  Once cleared, OTempInt is not reset if the die temperature remains above the thermal warning threshold and does not fall below +95°C.

# Table 2. DiLvl and LI Output

V <sub>DI</sub> (V)	DiLvl BIT	LI OUTPUT
< 5.2	0	High
> 8	1	Low

Table 3.  $\overline{\mathbf{Q}}\mathbf{L}\mathbf{v}\mathbf{l}$  and RX Output

V <sub>C/Q</sub> (V)	QLvI BIT	RX OUTPUT		
< 8	1	High		
>13	0	Low		

# **IO-Link Device Transceiver**

### CQConfig Register [R1, R0] = [0,1]

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Bit Name	RxFilter	HiSlew	C/Q_N/P	C/Q_PP	C/QDEn	Q	RxDis	C/QLoad
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR State	0	0	0	0	0	0	0	0

Use the CQConfig register to control the C/Q receiver and driver parameters. All bits in the CQConfig register are read-write and are set to 0 at power-up.

BIT	NAME	DESCRIPTION
D7	RxFilter	<b>C/Q and DI Receiver Filter Control.</b> The C/Q and DI receivers have analog lowpass filters to reduce high-frequency noise on the receiver inputs. Set the RxFilter bit to 0 to set the filter corner frequency to 500kHz. Set the RxFilter bit to 1 to set the filter corner frequency to 1MHz (this setting is used for high-speed COM3 operation).
		Noise filters on C/Q and DI are controlled simultaneously by the RxFilter bit.
D6	HiSlew	<b>Slew-Rate Control.</b> The HiSlew bit increases the slew rate for the C/Q and DO drivers and is used for high-speed COM3 (230kbps) data rates. Set HiSlew to 0 for COM1 and COM2 operation.
D5	C/Q_N/P	<b>C/Q Driver NPN/PNP Mode.</b> The C/Q_N/P bit selects between low-side (NPN) and high-side (PNP) modes when the C/Q driver is configured as an opendrain output (C/Q_PP = 0). Set C/Q_N/P to 1 to configure the driver for low-side (NPN) operation. Set C/Q_N/P to 0 for high-side (PNP) operation.
D4	C/Q_PP	<b>C/Q Driver Push-Pull Operation.</b> Set C/Q_PP to 1 to enable push-pull operation on the C/Q driver. The C/Q output is open-drain when C/Q_PP is 0.
D3	C/QDEn	<b>C/Q Driver Enable/Disable.</b> Set the C/QDEn bit to 1 to enable the C/Q driver. Set C/QDEn to 0 for hardware (TXEN) control. See Table 4.
D2	Q	<b>C/Q Driver Output Logic.</b> The Q bit can be used to program the C/Q output driver through software. The C/Q driver must be enabled and TXC = TXQ mus be high to control the C/Q driver through the Q bit (Figure 8). C/Q has the same logic polarity as the Q bit.
		Set the Q bit to 0 to control the C/Q driver with TXC and TXQ.
		The C/Q driver output state depends on the C/Q_PP and C/Q_N/P bits as shown in Table 5. Note that Table 5 assumes that the C/Q driver is enabled (TXEN = $V_L$ or C/QDEn = 1).
D1	RxDis	<b>C/Q Receiver Enable/Disable.</b> Set the RxDis bit to 1 to disable the C/Q receiver. The RX output is high when RxDis is 1.
D0	C/QLoad	<b>C/Q Current Sink Enable.</b> Set the C/QLoad bit to 1 to enable the internal current sink at C/Q.

# **IO-Link Device Transceiver**

Table 4. C/QDEn and TXEN C/Q Driver **Control** 

C/QDEn	TXEN	C/Q DRIVER
0	Low	Disabled
X	High	Enabled
1	X	Enabled



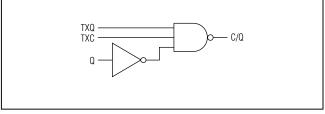


Figure 9. Equivalent C/Q Logic

**Table 5. C/Q Driver Output State** 

TXC AND TXQ (SEE NOTE)	Q	C/Q_PP	C/Q_N/P	C/Q CONFIGURATION	C/Q STATE
High	1	0	0	PNP, open drain	On, C/Q is high
High	0	0	0	PNP, open drain	Off, C/Q is high impedance
High	1	0	1	NPN, open drain	Off, C/Q is high impedance
High	0	0	1	NPN, open drain	On, C/Q is low
High	1	1	Х	Push-pull High	
High	0	1	Х	Push-pull	Low

**Note:** TXC and  $TXQ = V_L$ .

X = Don't care.

# **IO-Link Device Transceiver**

### DIOConfig Register [R1, R0] = [1,0]

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Bit Name	Dolnv	DoAv	DoN/P	DoPP	DoEn	DoBit	LiDis	DiLoad
Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
POR State	0	0	0	0	0	0	0	0

Use the DIOConfig register to control the DI and DO interfaces. All bits in the DIOConfig register are read-write and are set to 0 at power-up.

ert the logic of the DO e DoAv (Table 6). DO e polarity when both the
to enable antivalent TXQ inputs (and the Q
e DoAv bit is 1.
selects between low- e DO driver is configured to 1 to configure the o 0 for high-side (PNP)
oit to 1 to configure the an open-drain output
to enable the DO veak pulldown when
used to program the in to activate DoBit given in Table 7. Note
to disable the LI output.
to enable the internal

# **IO-Link Device Transceiver**

Table 6. DoAv and Dolnv Operation

DoAv	Dolnv	TXC AND TXQ (NOTE 1)	LO (NOTE 1)	DO (NOTE 2)	C/Q (NOTE 2)
0	0	Low	Low	High	High
0	0	Low	High	Low	High
0	0	High	Low	High	Low
0	0	High	High	Low	Low
0	1	Low	Low	Low	High
0	1	Low	High	High	High
0	1	High	Low	Low	Low
0	1	High	High	High	Low
1	0	Low	Low	Low	High
1	0	Low	High	Low	High
1	0	High	Low	High	Low
1	0	High	High	High	Low
1	1	Low	Low	High	High
1	1	Low	High	High	High
1	1	High	Low	Low	Low
1	1	High	High	Low	Low

**Note 1:** Low is when  $V_{TXC}$ ,  $V_{TXQ}$ , OR  $V_{LO}$  = 0V; high is when  $V_{TXC}$ ,  $V_{TXQ}$ , or  $V_{LO}$  =  $V_L$ .

**Note 2:** Low is when C/Q or DO < 8V; high is when C/Q or DO > 13V.

**Table 7. DO Output Programmed by DoBit** 

LO	DoBit	DoPP	DoN/P	DO CONFIGURATION	DO STATE
High	0	1	X	Push-pull	Low
High	1	1	X	Push-pull	High
High	0	0	0	PNP	Off, DO is high impedance
High	1	0	0	PNP	On, DO is high
High	0	0	1	NPN	On, DO is low
High	1	0	1	NPN	Off, DO is high impedance
Low	X	X	X	See Table 6	See Table 6

X = Don't care.

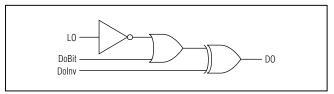


Figure 10. Equivalent DO Logic

# **IO-Link Device Transceiver**

### **Mode Register [R1, R0] = [1,1]**

Bit	D7	D6	D5	D4	D3	D2	D1	D0
Bit Name	RST	WuIntEn	DoFault	C/QFault	UV24	OTemp	UV33En	LDO33Dis
Read/Write	R/W	R/W	R	R	R	R	R	R/W
POR State	0	0	0	0	0	0	0	0

Use the Mode register to reset the MAX14821 and manage the 3.3V LDO. The Mode register has bits that represent the current status of fault conditions. When writing to the Mode register, the contents of the fault indication bits (bits 2 to 5) do not change.

BIT	NAME	DESCRIPTION		
D7	RST	<b>Register Reset.</b> Set RST to 1 to reset all registers to their default power-up state. Then set RST to 0 for normal operation.		
		The Status register is cleared and $\overline{IRQ}$ deasserts (if asserted) when RST = 1. Interrupts are not generated while RST = 1.		
D6	WuIntEn	<b>Wake-Up Interrupt Enable.</b> Set WulntEn to 1 to enable wake-up interrupt generation. When WulntEn is set, the Wulnt bit in the Status register is set and $\overline{IRQ}$ asserts when a valid wake-up condition is detected. The C/Q driver must be enabled for wake-up detection. The state of WulntEn does not affect the $\overline{WU}$ output. See the <i>Wake-Up Detection</i> section for more information.		
D5	DoFault	<b>DO Fault Status.</b> The DoFault bit is set when a short circuit or voltage fault occurs at the DO driver output (see the <i>DO Fault Detection</i> section for more information). The DoFault and DoFaultInt bits are both set when a fault occurs on DO. DoFault is cleared when the fault is removed.		
D4	C/QFault	<b>C/Q Fault Status.</b> The C/QFault bit is set when a short circuit or voltage fault occurs at the C/Q driver output (see the <i>C/Q Fault Detection</i> section for more information). The C/QFault and C/QFaultInt bits are both set when a fault occurs on C/Q. C/QFault is cleared when the fault is removed.		
D3	UV24	$V_{CC}$ Undervoltage Condition. Both the UV24 and the UV24Int bits are set when $V_{CC}$ falls below $V_{CCUVLO}$ . UV24 is cleared when $V_{CC}$ rises above the $V_{CC}$ threshold. $V_5$ must be present for $V_{CC}$ undervoltage monitoring.		
D2	OTemp	<b>Temperature Warning.</b> The OTemp bit is set when a high-temperature condition occurs on the device. Both the OTempInt interrupt in the Status register and the OTemp bit are set when the junction temperature of the die rises to above +115°C (typ). The OTemp bit is cleared when the junction temperature falls below +95°C (typ).		
D1	UV33En	<b>LDO33 UV Enable.</b> Set the UV33En bit to 1 to assert the UV output when LDO33 voltage falls below the 2.4V (typ) undervoltage-lockout threshold. The UV33En bit does not affect the UV33Int bit in the Status register; $\overline{IRQ}$ asserts when $V_{LDO33}$ falls below $V_{LDO33UVLO}$ regardless of the state of UV33En.		
D0	LDO33Dis	<b>LDO33 Enable/Disable.</b> Set LDO33Dis to 1 to disable the 3.3V linear regulator (LDO33).		

## **IO-Link Device Transceiver**

#### **SPI Interface**

The device communicates through an SPI-compatible 4-wire serial interface. The interface has three inputs—clock (SCLK), chip select  $(\overline{CS})$ , and data in (SDI)—and one output, data out (SDO). The maximum SPI clock rate

for the device is 12MHz. The SPI interface complies with clock polarity CPOL = 0 and clock phase CPHA = 0 (see Figure 11 and Figure 12).

The SPI interface is not available when  $\mathsf{V}_5$  or  $\mathsf{V}_\mathsf{L}$  are not present.

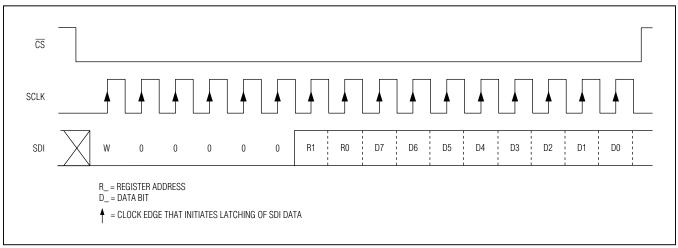


Figure 11. SPI Write Cycle

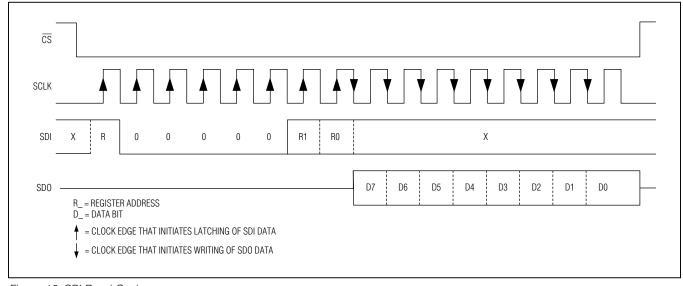


Figure 12. SPI Read Cycle

## **IO-Link Device Transceiver**

### **Applications Information**

#### **UART Interfacing**

The logic levels of the microcontroller interface I/Os (TXC, TXQ, TXEN, and RX) are defined by  $V_L$ .

The device can be interfaced to microcontrollers where the on-board UART TX output cannot be programmed as a logic output (GPO). In this case, connect the TX output of the UART to the TXC input for IO-Link communication and connect a separate GPO output on the microcontroller to TXQ for standard IO (SIO) mode operation (Figure 13). As the TXQ and TXC inputs are internally logically ANDed, the unused input (TXC or TXQ) must be held high while the other is in operation.

#### **Transient Protection**

Inductive load switching, surges, and bursts create high transient voltages. C/Q, DO, and DI should be protected against high overvoltage and undervoltage transients. Positive voltage transients on C/Q, DO, and DI must be limited to +55V relative to GND and negative voltage transients must be limited to -55V (relative to V<sub>CC</sub>) on DO and C/Q and to -55V (relative to GND) on DI. Figure 14 shows suitable protection using TVS diodes to meet both the IEC 61000-4-2 ESD and IEC 61000-4-5 surge testing. Other protection schemes may also be suitable.

The device has to be protected against transients that occur during hot-plugging of the L+ sensor supply (VCC input). This is achieved by placing a  $10\Omega$  resistor with  $1\mu F$  capacitor before LDOIN and connecting an RC between the sensor supply input and the VCC pin, as shown in Figure 14. The RC time constant of the filter on VCC should be larger or equal to  $0.8\mu s$ . In case that VL is supplied by V5 and the bypass capacitor on V5 is 100nF, the  $10\Omega$  resistor in series with LDOIN is not needed.

#### **Optional External Powering**

The MAX14821 is powered by  $V_{CC}$  and  $V_5$ .  $V_L$  is a reference voltage input to set the logic levels of the microcontroller interface. The logic and SPI interface are operational when  $V_5$  and  $V_L$  are present even if  $V_{CC}$  is not present.

The  $V_P$  output provides a reverse-polarity-protected voltage one diode drop below  $V_{CC}$  and can be used for supplying external circuitry, like power supplies. The current drawn from  $V_P$  cannot exceed 50mA. Be aware that capacitance on  $V_P$  can cause transient currents at power-up equal to  $C \times dV_{CC}/dt$ .

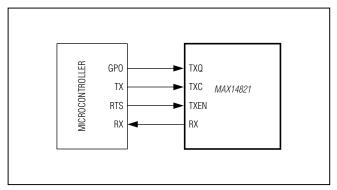


Figure 13. UART Interface

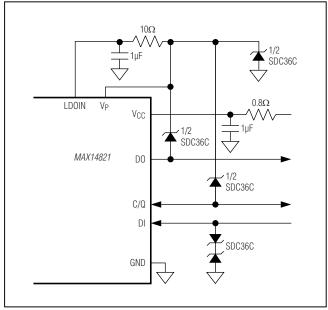


Figure 14. MAX14821 Operating Circuit with TVS Protection

In order to reduce power dissipated in the device, an reverse protection diode can be used to power the external circuitry, instead of using VP, as shown in Figure 15.

 $\rm V_5$  is typically powered by the internal 5V regulator, but can alternatively be powered by an external 5V regulator. When powering  $\rm V_5$  externally, connect LDOIN to  $\rm V_5$ . (Figure 15). This configuration disables operation of the internal 5V regulator and reduces the on-chip power consumption.

When an external 5V regulator is used to power V5, the V5 bypass capacitance is determined by that regulator, and is not limited to 100nF.

# **IO-Link Device Transceiver**

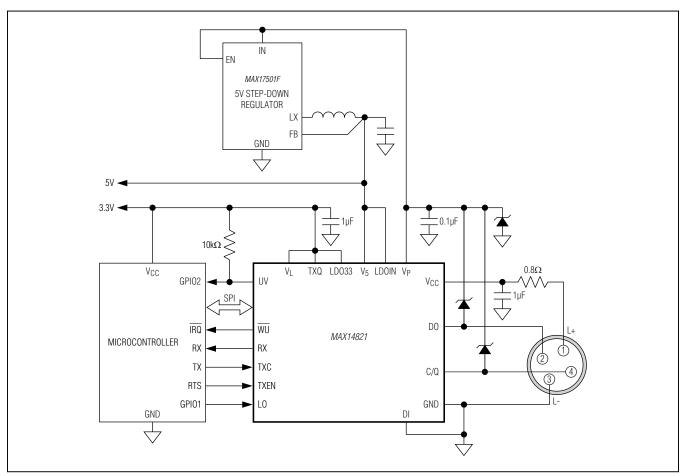


Figure 15. Using an Optional External Supply to Power the MAX14821

### **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX14821ETG+	-40°C to +85°C	24 TQFN-EP*
MAX14821EWA+**	-40°C to +85°C	25 WLP

<sup>+</sup>Denotes a lead(Pb)-free/RoHS-compliant package.

### **Chip Information**

PROCESS: BiCMOS

### **Package Information**

For the latest package outline information and land patterns (foot-prints), go to <a href="https://www.maximintegrated.com/packages">www.maximintegrated.com/packages</a>. Note that a "+", "#", or "-" in the package code indicates RoHS status only. Package drawings may show a different suffix character, but the drawing pertains to the package regardless of RoHS status.

PACKAGE TYPE	PACKAGE CODE	OUTLINE NO.	LAND PATTERN NO.
24 TQFN-EP	T2444+4	21-0139	90-0022
25 WLP	W252A2+1	21-0191	Application Note 1891

<sup>\*</sup>EP = Exposed pad.

<sup>\*\*</sup>Future product—contact factory for availability.

# **IO-Link Device Transceiver**

### **Revision History**

REVISION NUMBER	REVISION DATE	DESCRIPTION	PAGES CHANGED
0	8/11	Initial release	_
1	12/11 Corrected data line direction for <i>Typical Operating Circuit</i> , removed TOC 14 and added new TOC 17, corrected <i>DO Fault Detection</i> section, corrected <i>Thermal Shutdown</i> section, corrected IEC number in <i>Transient Protection</i> section, corrected Figures 11 and 14		1, 13, 17, 18, 26, 28
2	7/12 Updated formula in <i>Thermal Protection and Considerations</i> section, updated <i>Optional External Powering</i> section, updated Figure 14		18, 27, 28
3	3/14	Added need for RC filter before LDOIN Corrected autoretry timing Corrected trademark on page Added application information and application circuit for use of larger LDO bypass capacitors Improved SPI description in figures	1, 16-17, 22, 24, 26-28



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# **IO-Link Device Transceiver**

# **IO-Link Device Transceiver**